In the Specification:

Please add a new section directly before the TECHNICAL FIELD on page 1 as follows:

CROSS-REFERENCE TO RELATED APPLICATION

This application is a divisional application of U.S. Patent Application No. 10/190,019, entitled "MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR CONTROLLING THE DISPOSITION OF NON-CONDUCTIVE MATERIALS IN SUCH PACKAGES", filed July 5, 2002, now U.S. Patent No. _____, issued on _____, which is incorporated herein by reference in its entirety.

Please replace paragraph 0023 with the following:

In one embodiment, the dimensions of the fluid flow channel 161 can be selected according to design criteria that account for fluid flow rate, package geometry and/or support for the conductive couplers 150. For example, the fluid flow channel 161 can have a transverse or widthwise dimension W that is determined by the spacing between neighboring conductive couplers 150 and/or by the amount of non-conductive material 160 selected to strengthen the connection between the conductive couplers 150 and the first connection sites 133. The depthwise dimension D of the flow channel 161 can be determined based on the height of the conductive couplers 150 and/or by the amount of non-conductive material 160 selected to strengthen the connection between the conductive couplers ~~160~~150 and the first connection sites 133. Based on these criteria, the fluid flow channel 161 can have a variety of dimensions, and can range from a relatively small channel (e.g., offset from the sides of neighboring conductive couplers 150 and offset the first surface 131 of the microelectronic substrate 120), to a relatively large channel (extending transversely to expose the sides of neighboring conductive couplers 150, and extending depthwise to expose the first surface 131). When the package 110 includes larger fluid flow channels 161, the non-conductive material 160 can be reduced in size to a small ring around each first connection site 133.